



PCN#20151027001

Qualification of NFME Additional Assembly & Test site for Select TO220 Packaged Devices
Change Notification / Sample Request

Date: 10/30/2015
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20151027001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CSD19505KCS	null
CSD19506KCS	null
CSD19535KCS	null
CSD19536KCS	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20151027001			PCN Date:	10/30/2015												
Title:	Qualification of NFME Additional Assembly & Test site for Select TO220 Packaged Devices																
Customer Contact:	PCN Manager		Dept:	Quality Services													
Proposed 1st Ship Date:	1/30/2016		Estimated Sample Availability:	Provided upon Request													
Change Type:																	
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials													
<input type="checkbox"/> Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification													
<input checked="" type="checkbox"/> Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process													
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process													
<input type="checkbox"/> Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process													
	<input type="checkbox"/>	Part number change															
PCN Details																	
Description of Change:																	
<p>Texas Instruments is pleased to announce the qualification of Nantong Fujitsu Microelectronics (NFME) as an additional Assembly & Test site for select devices in the TO220 package shown in the table below. BOM differences are noted as follows:</p> <table border="1"> <thead> <tr> <th></th> <th>ASEWH</th> <th>NFME</th> </tr> </thead> <tbody> <tr> <td>Mount Compound</td> <td>SID#A-11</td> <td>SID#1110999A2</td> </tr> <tr> <td>Mold Compound</td> <td>SID#4020026A3</td> <td>SID#R12</td> </tr> <tr> <td>Gate Bond Wire</td> <td>Al, 3.0 mils</td> <td>Al, 5.0 mils</td> </tr> </tbody> </table>							ASEWH	NFME	Mount Compound	SID#A-11	SID#1110999A2	Mold Compound	SID#4020026A3	SID#R12	Gate Bond Wire	Al, 3.0 mils	Al, 5.0 mils
	ASEWH	NFME															
Mount Compound	SID#A-11	SID#1110999A2															
Mold Compound	SID#4020026A3	SID#R12															
Gate Bond Wire	Al, 3.0 mils	Al, 5.0 mils															
<p>Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.</p>																	
Reason for Change:																	
Continuity of Supply																	
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																	
None																	
Anticipated impact on Material Declaration																	
<input type="checkbox"/> No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .															
Changes to product identification resulting from this PCN:																	
Assembly Site	Assembly Site Origin (22L)		Assembly Country Code (21L)		Assembly City												
ASEWH	AWH		CHN		Weihai												
NFME	NFM		CHN		Economic Development Zone												

Sample product shipping label (not actual product label)



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CS0:SHE (21L) CCO:USA
(22L) AS0:MLA (23L) ACO:MYS

Topside Device marking:

Assembly site code for ASEWH= I

Assembly site code for NFME = E

Product Affected

CSD19505KCS

CSD19506KCS

CSD19535KCS

CSD19536KCS

Qualification Report

Offload - 19505/19535/19506/19536 to NFME Approve Date 25-Sep-2015

Product Attributes

Attributes	Qual Device: CSD19505KCS	Qual Device: CSD19506KCS	Qual Device: CSD19535KCS	Qual Device: CSD19536KCS
Assembly Site	NFME	NFME	NFME	NFME
Package Family	TO-220	TO-220	TO-220	TO-220
Flammability Rating	UL-94V-0	UL-94V-0	UL-94V-0	UL-94V-0
Wafer Fab Supplier	CFAB	CFAB	CFAB	CFAB
Wafer Fab Process	N35UMV09L2P1M0C6	N35UMV09L2P1M0C6	N35UMV09L2P1M0C6	N35UMV09L2P1M0C6

- QBS: Qual By Similarity
- Qual Device CSD19506KCS is qualified at NC-P
- Qual Device CSD19536KCS is qualified at NC-P
- Qual Device CSD19505KCS is qualified at NC-P
- Qual Device CSD19535KCS is qualified at NC-P

ASEWH KCS 80V & 100V Qualification Summary

CSD19536KCS Qualification Test Summary				
Stress	Conditions	Test Duration	Sample Size	Results
HTRB	175°C/80% Rated Vds	1K hrs	3 lots x 77 units	Pass
HTGB	175°C/80% Rated Vgs	1K hrs	3 lots x 77 units	Pass
THB	85°C/85%R.H./80% Rated Vds	1K hrs	3 lots x 77 units	Pass
Autoclave	121C/100% RH	96 hrs	3 lots x 77 units	Pass
Intermittent Op Life	Delta T _j = 100°C 2 min on/2 min off	10K cycles	3 lots x 77 units	Pass
Temp Cycle	-65°C to 150°C	500 cycles	3 lots x 77 units	Pass

Pass = 0/77 x 3 lots

Preconditioning performed on devices prior to THB, Autoclave, & Temp Cycle stresses

- Bake: 24 hours @ 125°C
- 3X reflow + flux + rinse, 260°C Pb free reflow temp

The CSD19505KCS, CSD19506KCS & CSD19535KCS were qualified by similarity and verified by performing qualification tests to the conditions shown in the table below:

CSD19505KCS, CSD19506KCS, & CSD19535KCS Qualification Test Summary				
Stress	Conditions	Test Duration	Sample Size	Results
HTRB	175°C/80% Rated Vds	168 hrs	1 lot x 77 units	Pass
HTGB	175°C/80% Rated Vgs	168 hrs	1 lot x 77 units	Pass

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CSD19505KCS	Qual Device: CSD19506KCS	Qual Device: CSD19535KCS	Qual Device: CSD19536KCS
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	3/1/0	3/1/0	3/1/0	3/1/0

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com